

Title (en)
HEAT SINK, AND ASSEMBLY OR MODULE UNIT COMPRISING A HEAT SINK

Title (de)
WÄRMESENKE SOWIE BAU- ODER MODULEINHEIT MIT EINER WÄRMESENKE

Title (fr)
PUITS DE CHALEUR ET MODULE OU UNITE MODULAIRE PRESENTANT UN Puits DE CHALEUR

Publication
EP 2132772 A2 20091216 (DE)

Application
EP 07846389 A 20071204

Priority

- DE 2007002186 W 20071204
- DE 102007015771 A 20070330
- DE 102007027991 A 20070614
- DE 102007030389 A 20070629

Abstract (en)
[origin: WO2008119309A2] Disclosed is a heat sink for cooling parts, subassemblies, modules, or similar components, particularly for cooling electrical or electronic components. Said heat sink comprises at least one cooling element which forms at least one cooling area for connecting the component that is to be cooled and which is made of a metallic material in said cooling area.

IPC 8 full level
H01L 23/373 (2006.01); **H01S 5/024** (2006.01)

CPC (source: EP US)
H01L 23/3735 (2013.01 - EP US); **H01S 5/02476** (2013.01 - EP US); **H05K 7/20481** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H01L 24/73** (2013.01 - EP US); **H01L 25/072** (2013.01 - EP US); **H01L 25/18** (2013.01 - EP US); **H01L 2224/32225** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48137** (2013.01 - EP US); **H01L 2224/48139** (2013.01 - EP US); **H01L 2224/48227** (2013.01 - EP US); **H01L 2224/48472** (2013.01 - EP US); **H01L 2224/73265** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/01019** (2013.01 - EP US); **H01L 2924/0102** (2013.01 - EP US); **H01L 2924/01068** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H01L 2924/01322** (2013.01 - EP US); **H01L 2924/13055** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US); **H01S 5/0237** (2021.01 - EP US); **H01S 5/02423** (2013.01 - EP US); **H01S 5/02469** (2013.01 - EP US); **H01S 5/4025** (2013.01 - EP US); **H05K 1/0306** (2013.01 - EP); **H05K 3/0061** (2013.01 - EP)

C-Set (source: EP US)
EP

1. **H01L 2224/48472 + H01L 2224/48227 + H01L 2924/00**
2. **H01L 2224/73265 + H01L 2224/32225 + H01L 2224/48227 + H01L 2924/00012**
3. **H01L 2224/48091 + H01L 2924/00014**
4. **H01L 2224/48472 + H01L 2224/48091 + H01L 2924/00**
5. **H01L 2924/00014 + H01L 2224/45099**
6. **H01L 2924/00014 + H01L 2224/45015 + H01L 2924/207**
7. **H01L 2924/181 + H01L 2924/00012**

US

1. **H01L 2224/48472 + H01L 2224/48227 + H01L 2924/00**
2. **H01L 2224/73265 + H01L 2224/32225 + H01L 2224/48227 + H01L 2924/00012**
3. **H01L 2224/48091 + H01L 2924/00014**
4. **H01L 2224/48472 + H01L 2224/48091 + H01L 2924/00**
5. **H01L 2924/00014 + H01L 2224/45099**
6. **H01L 2924/00014 + H01L 2224/45015 + H01L 2924/207**
7. **H01L 2924/181 + H01L 2924/00**

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC MT NL PL PT RO SE SI SK TR

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